



FIG. 1A

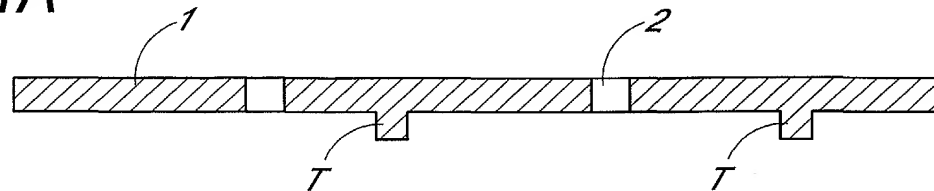


FIG. 1B

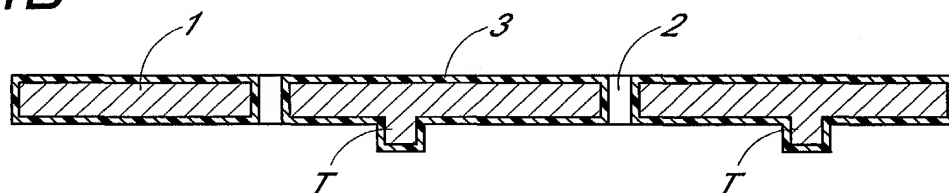


FIG. 1C

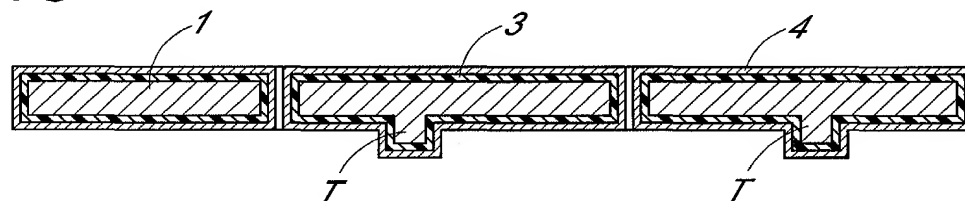


FIG. 1D

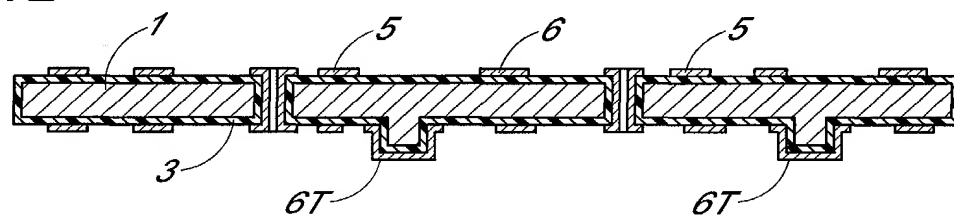


FIG. 1E

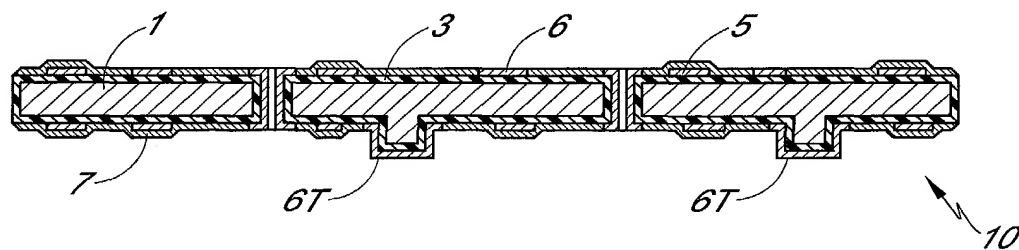




FIG. 2

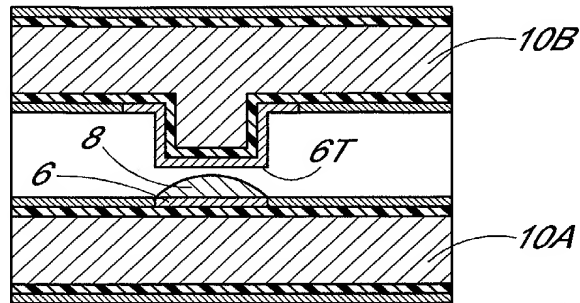


FIG. 3A

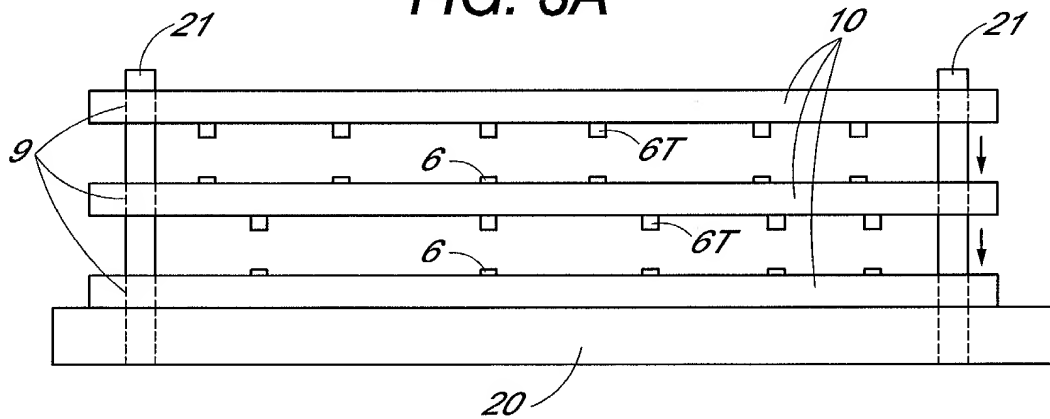
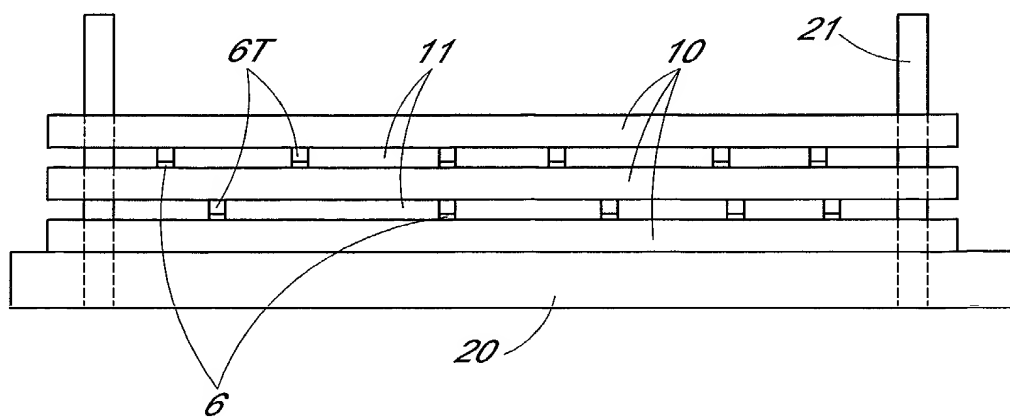


FIG. 3B





MULTILAYER CIRCUIT BOARD

Ishiwa, et al

Appl. No.: 09/779,691 · Atty Docket: SANWA1.001AUS

3 / 6

FIG. 4A

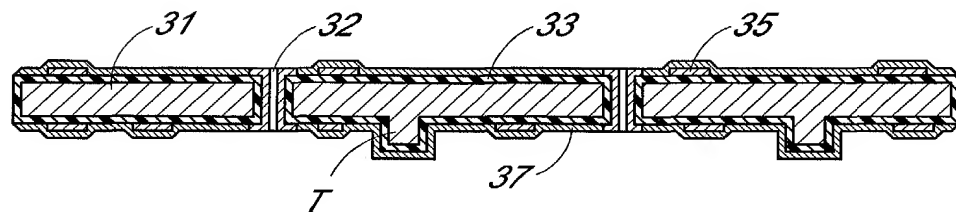


FIG. 4B

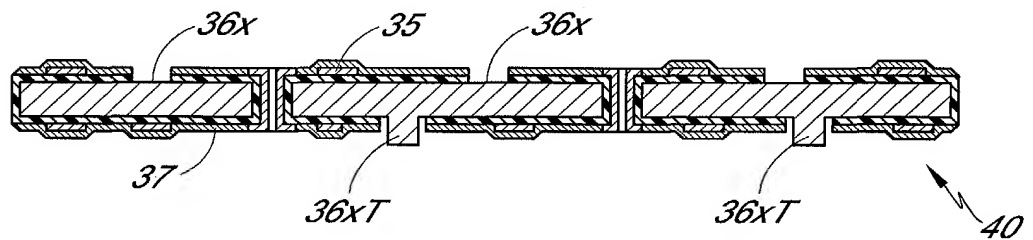


FIG. 4C

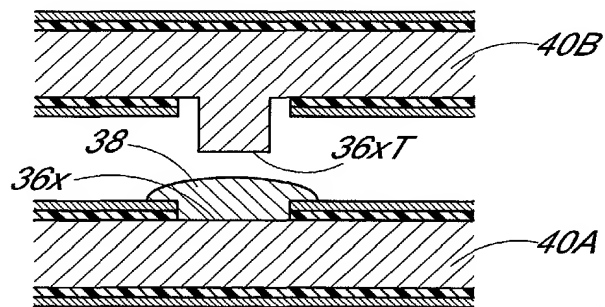




FIG. 5A

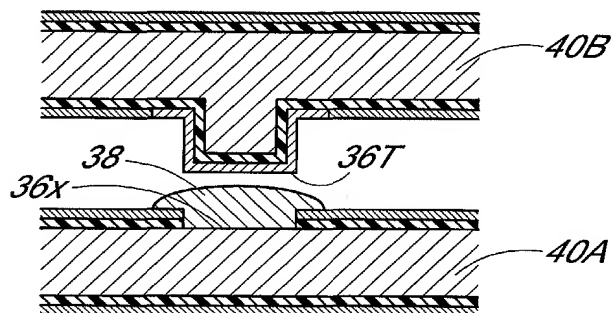


FIG. 5B

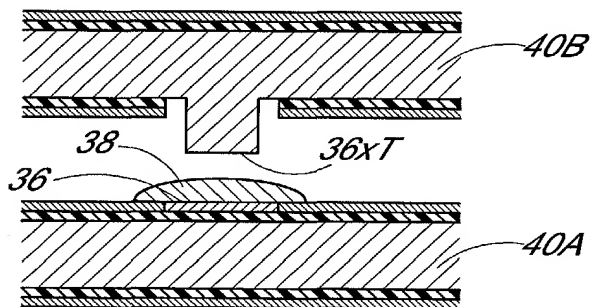


FIG. 10

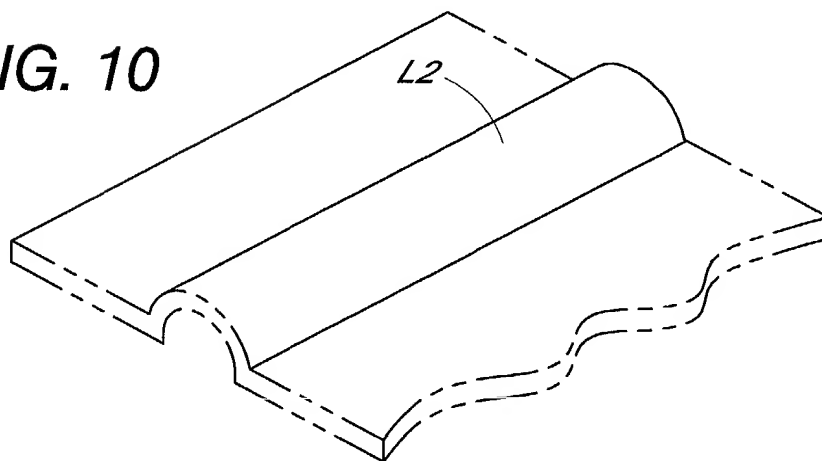




FIG. 6

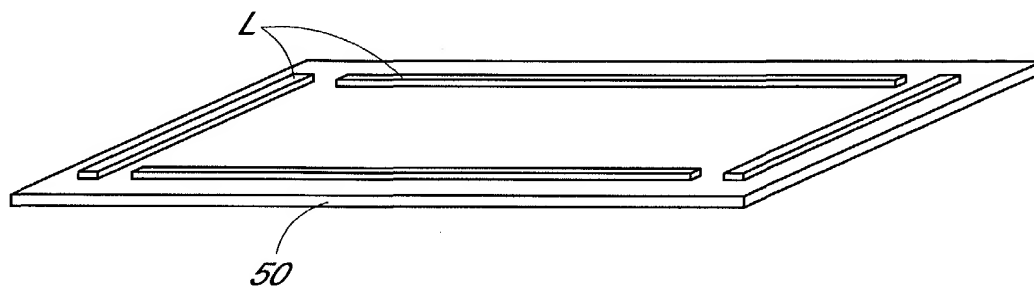


FIG. 7A

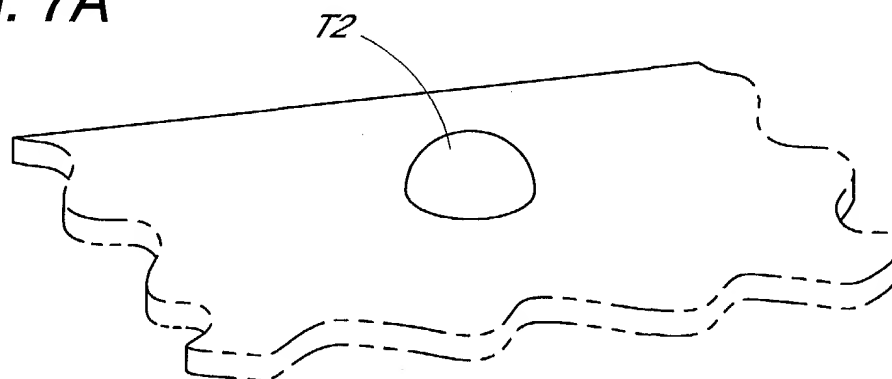
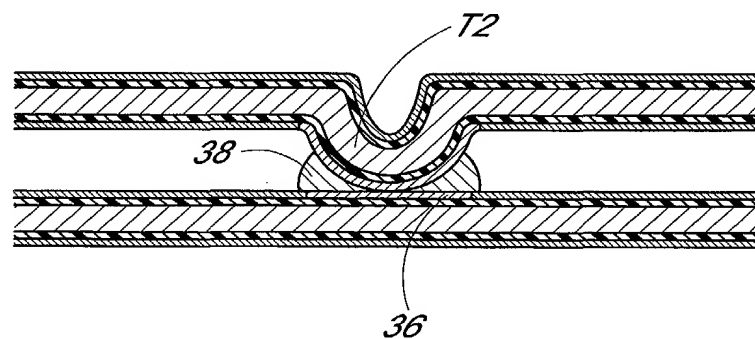


FIG. 7B





MULTILAYER CIRCUIT BOARD

Ishiwa, et al

Appl. No.: 09/779,691 Atty Docket: SANWA1.001AUS

6 / 6

FIG. 8A

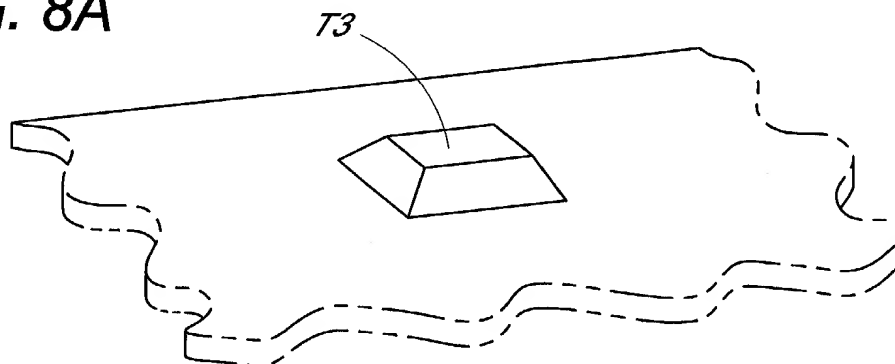


FIG. 8B

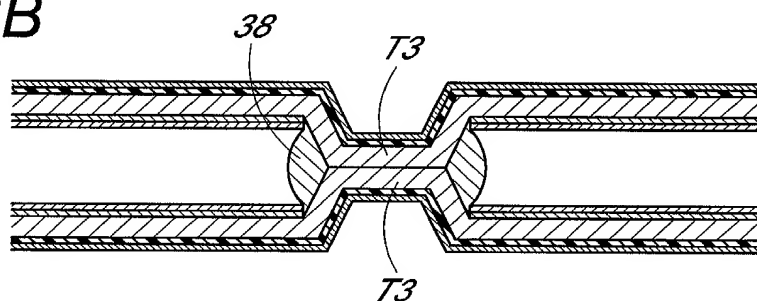


FIG. 9A

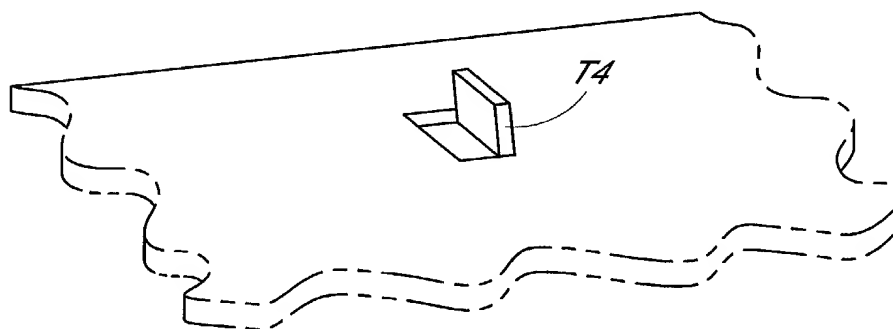


FIG. 9B

